

## JIANGYIN CHANGDIAN ADVANCED PACKAGING CO., LTD.

HEAD OFFICE: NO. 8, SANGDELAN ROAD, WUYUAN STREET, HAIYAN COUNTY, 314000, JIAXING CITY, ZHEJIANG PROVINCE, CHINA

Unified social credit code: 91320281753943521E

This is a multi-site certificate, additional site details are listed in the appendix to this certificate

Bureau Veritas Certification Holding SAS - UK Branch certifies that the Management System of the above organisation has been audited and found to be in accordance with the requirements of the management system standards detailed below

ISO 9001:2015

Scope of certification

## Wafer Bumping and Wafer Level Chip Scale Packages / 3D packages with Testing

Original cycle start date:

11 OCTOBER 2011

Expiry date of previous cycle:

NA

Certification / Recertification audit date:

NA

Certification / Recertification cycle start date:

**03 SEPTEMBER 2018** 

Subject to the continued satisfactory operation of the organisation's Management System,

this certificate expires on:

02 SEPTEMBER 2021

Certificate No.: CNBJ312842-UK

Version: No.01, Revision 03 SEPTEMBER 2018





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Certification body address: 5<sup>th</sup> Floor, 66 Prescot Street, London E1 8HG, United Kingdom. Local office address: Rm. B, F4, No.1288, Waima Road, Huangpu District, Shanghai, China. 200011.

Further clarifications regarding the scope of this certificate and the applicability of the management system requirements may be obtained by consulting the organisation.

To check this certificate validity please call: (+86 21 23190329)

Certified organisation has to accept and pass regular surveillance audits, then this certificate can be continuously valid. Information of this certificate may be obtained by visiting CNCA website (www.cnca.gov.cn).



## JIANGYIN CHANGDIAN ADVANCED PACKAGING CO., LTD.

ISO 9001:2015

Scope of certification

## Wafer Bumping and Wafer Level Chip Scale Packages / 3D packages with Testing.

Site Name/Location	Site Addition Date	Site Address	Site Scope
Registered Address	30 October 2003	No.99,Changjiang East Road, High Technology Development Industry Park, Jiangyin City, Jiangsu Province, P. R. China	Wafer Bumping and Wafer Level Chip Scale Packages / 3D packages with Testing
Operational Address 1	20 January 2017	B1: No.275 Binjiang Rd, Jiangyin, Jiangsu, P. R. China	
Operational Address 2	20 January 2017	B2: No.78 Changshan Rd, Jiangyin, Jiangsu, P. R. China	

Certificate No. : CNBJ312842-UK Version: No.01, Revision date: 03 SEPTEMBER 2018

Signed on behalf of BVCH SAS UK Branch

(www.cnca.gov.cn).

U K A S MANAGEMENT SYSTEMS

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